

# NCEP60T20D

# **NCE N-Channel Super Trench Power MOSFET**

#### **Description**

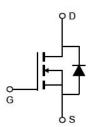
The NCEP60T20D uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of  $R_{\text{DS}(\text{ON})}$  and  $Q_g$ . This device is ideal for high-frequency switching and synchronous rectification.

#### **General Features**

- V<sub>DS</sub> =60V,I<sub>D</sub> =200A
  R<sub>DS(ON)</sub>=1.8mΩ (typical) @ V<sub>GS</sub>=10V
- Excellent gate charge x R<sub>DS(on)</sub> product
- Very low on-resistance R<sub>DS(on)</sub>
- 175 °C operating temperature
- Pb-free lead plating
- 100% UIS tested

#### **Application**

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification



Schematic diagram



TO-263T-2L top view

100% UIS TESTED!

100% AVds TESTED!

### **Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCEP60T20D	NCEP60T20D	TO-263-2L	-	-	-

# Absolute Maximum Ratings (T<sub>c</sub>=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	60	V	
Gate-Source Voltage	V <sub>G</sub> s	±20	V	
Drain Current-Continuous (Silicon Limited)	I <sub>D</sub>	200	Α	
Drain Current-Continuous(Tc=100 ℃)	I <sub>D</sub> (100°C)	150	А	
Pulsed Drain Current	I <sub>DM</sub>	800	Α	
Maximum Power Dissipation	P <sub>D</sub>	255	W	
Derating factor		1.7	W/℃	
Single pulse avalanche energy (Note 1)	E <sub>AS</sub>	2000	mJ	
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55 To 175	°C	

#### **Thermal Characteristic**

Thermal Resistance,Junction-to-Case	R <sub>θJC</sub>	0.59	°C/W
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# NCEP60T20D

# Electrical Characteristics (T<sub>C</sub>=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•			
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	60		-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =60V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics						
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS},I_{D}=250\mu A$	2.2	3.0	4.0	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =100A	-	1.8	2.2	mΩ
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =10V,I <sub>D</sub> =100A	-	60	-	S
Dynamic Characteristics				,		
Input Capacitance	C <sub>lss</sub>	V <sub>DS</sub> =30V,V <sub>GS</sub> =0V,	-	9200	-	PF
Output Capacitance	Coss		-	1900	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.0MHz	-	61	-	PF
Switching Characteristics (Note 2)				,		
Turn-on Delay Time	t <sub>d(on)</sub>		-	23	-	nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =30 $V,I_{D}$ =100 $A$	-	19	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =10 $V$ , $R_{G}$ =4.7 $\Omega$	-	58	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	14	-	nS
Total Gate Charge	Qg	V 20VI 400A	-	130		nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =30V, $I_{D}$ =100A, $V_{GS}$ =10V	-	40.6		nC
Gate-Drain Charge	Q <sub>gd</sub>		-	23.9		nC
Drain-Source Diode Characteristics				,		
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =200A	-		1.2	V
Diode Forward Current	Is		-	-	120	Α
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25°C, I <sub>F</sub> = I <sub>S</sub>	-	67		nS
Reverse Recovery Charge	Qrr	di/dt = 100A/μs	-	112		nC

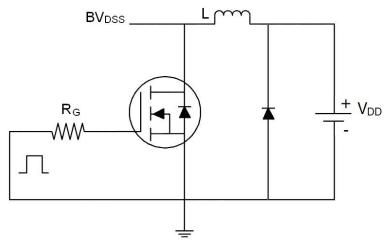
#### Notes:

- 1.EAS condition : Tj=25°C,VDD=30V,VG=10V,L=0.5mH,Rg=25 $\Omega$
- 2.Guaranteed by design, not subject to production
- 3. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsin k, assuming a maximum junction temperature of  $TJ(MAX)=175^{\circ}$  C. The SOA curve provides a single pulse rating.

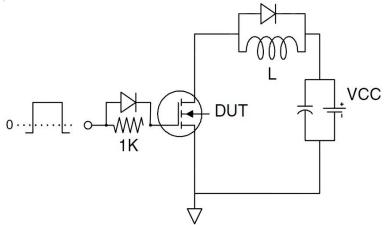


# **Test Circuit**

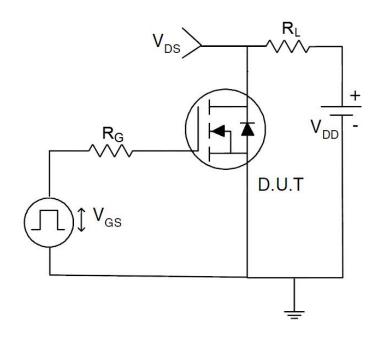
# 1) E<sub>AS</sub> test Circuit



# 2) Gate charge test Circuit

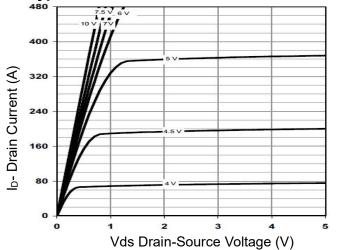


## 3) Switch Time Test Circuit

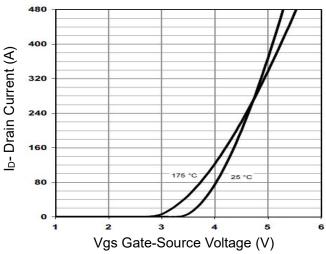




#### Typical Electrical and Thermal Characteristics



**Figure 1 Output Characteristics** 



**Figure 2 Transfer Characteristics** 

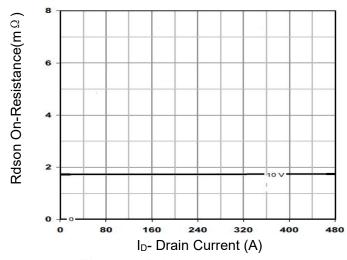


Figure 3 Rdson- Drain Current

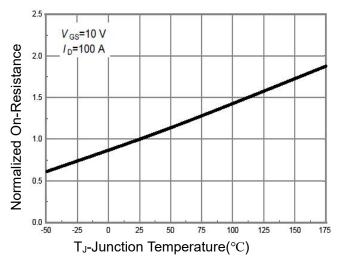


Figure 4 Rdson-JunctionTemperature

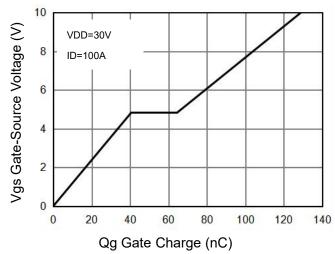


Figure 5 Gate Charge

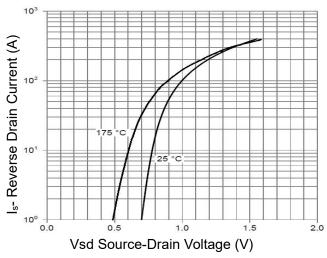


Figure 6 Source- Drain Diode Forward

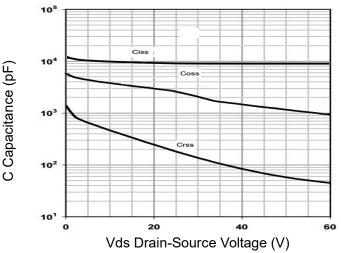


Figure 7 Capacitance vs Vds

1000

100

10

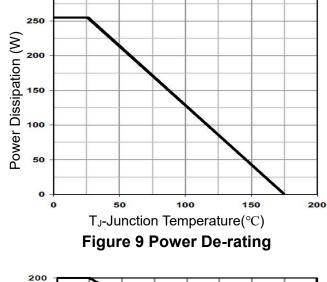
1

0.1

0.01 0.01

0.1

Ip- Drain Current (A)



1000

10us

00us

10ms

100

180 160 Ip- Drain Current (A) 140 120 100 80 60 40 20 o T<sub>J</sub>-Junction Temperature (°C)

300

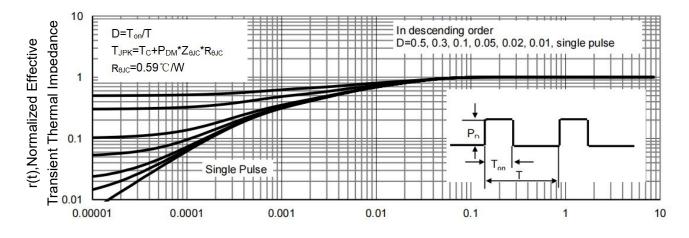
Vds Drain-Source Voltage (V) Figure 8 Safe Operation Area(Note3)

10

Figure 10 Current De-rating

100

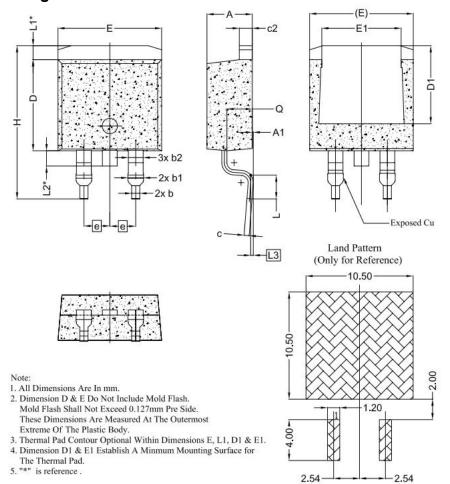
125



Square Wave Pluse Duration(sec)

**Figure 11 Normalized Maximum Transient Thermal Impedance** 

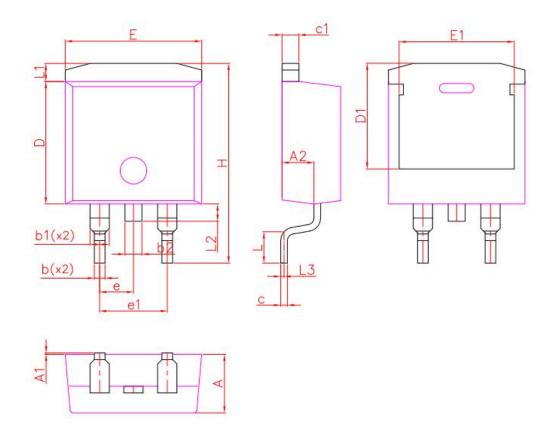
# TO-263-2L(G) Package Information



SYMBOL	DIMENSIONS			
SYMBOL	MIN.	NOM.	MAX.	
Α	4.24	4.44	4.64	
A1	0.00	0.10	0.25	
b	0.70	0.80	0.90	
b1	1.20	1.55	1.75	
b2	1,20	1,45	1,70	
С	0.40	0.50	0.60	
c2	1.15	1.27	1.40	
D	8.82	8.92	9.02	
D1	6.86	7.65	122	
E	9.96	10.16	10.36	
E1	6.89	7.77	7.89	
е		2.54 BSC	00 00	
н	14.61	15.00	15.88	
L	1.78	2.32	2.79	
L1	1.36 REF.			
L2	1.50 REF.			
L3	0.25 BSC			
Q	2.30	2.48	2.70	

# NCEP60T20D

# TO-263-2L(E) Package Information



	TC	263		
DIM.	MIN.	NOM.	MAX.	
Α	4.20	4.40	4.60	
A1	0.00	0.10	0.25	
A2	2.20	2.40	2.60	
b	0.70	0.80	0.90	
b1	1.20	1.45	1.75	
b2	1.17	1.27	1.37	
С	0.40	0.50	0.60	
c1	1.15	1.27	1.40	
D	9.10	9.20	9.30	
D1	7.63	7.93	8.23	
E	10.05	10.25	10.45	
E1	8.35	8.65	8.95	
e		2.54BSC		
e1		5.08BSC		
Н	14.61	15.00	15.88	
L	1.78	2.35	2.79	
L1	1.36REF			
L2	1.3REF			
L3		0.25REF		
All	dimension	s in millim	eters	



#### http://www.ncepower.com

Pb Free Product

NCEP60T20

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